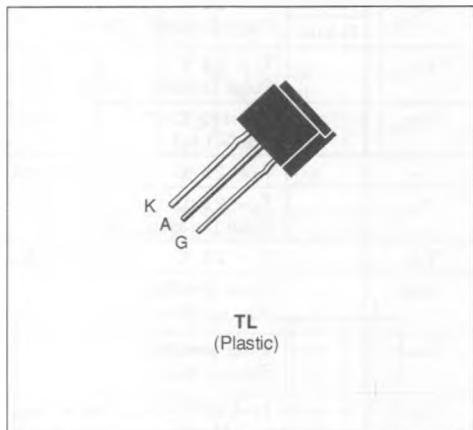


SENSITIVE GATE THYRISTORS

- OPERATES DIRECTLY FROM LOW SIGNAL
- GLASS PASSIVATED CHIP
- HIGH STABILITY AND RELIABILITY
- HIGH ON-STATE CURRENT



ABSOLUTE RATINGS (limiting values)

Symbol	Parameter	Value	Unit
I_T (RMS)	RMS on-state Current (1)	4	A
I_T (AV)	Mean on-state Current (1)	2.5	A
I_{TSM}	Non Repetitive Surge Peak on-state Current (T_j initial = 25 °C) (2)	t = 8.3 ms	A
		t = 10 ms	A
I^2t	I^2t Value for Fusing	6	A^2s
di/dt	Critical Rate of Rise of on-state Current (3)	100	$A/\mu s$
T_{stg} T_j	Storage and Operating Junction Temperature Range	- 40 to 150	°C
		- 40 to 110	°C

Symbol	Parameter	TLS106-.. or TLS107-..					Unit
		05	1	2	4	6	
V_{DRM} V_{RRM}	Repetitive Peak off-state Voltage (4)	50	100	200	400	600	V

(1) Single phase circuit, 180° conduction angle.

(2) Half sine wave.

(3) $I_G = 5 \text{ mA}$ $\text{di}/\text{dt} = 1 \text{ A}/\mu \text{s}$.

(4) $T_j = 110 \text{ }^\circ\text{C}$ $R_{GK} = 1 \text{ k}\Omega$.

THERMAL RESISTANCES

Symbol	Parameter	Value	Unit
$R_{th(j-i)}$	Junction-leads	15	°C/W
$R_{th(j-a)}$	Junction-ambient on Printed Circuit (with Cu 1 cm ²)	50	°C/W

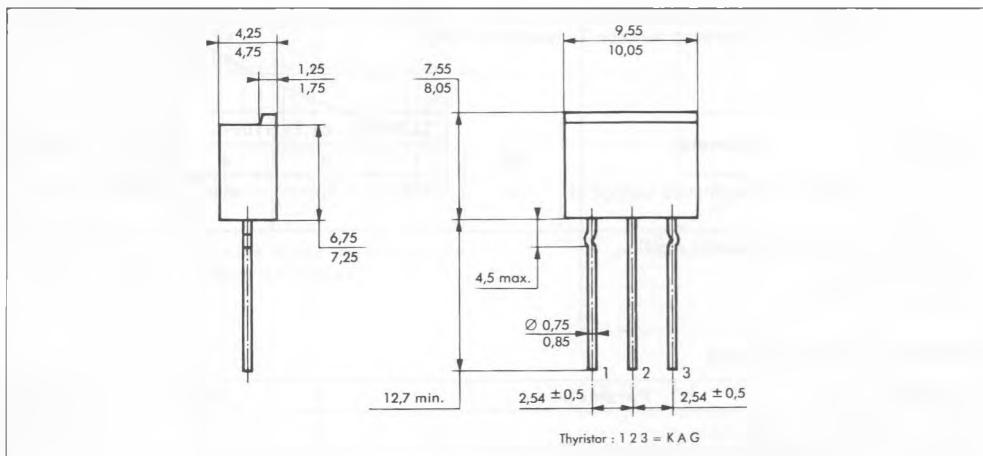
GATE CHARACTERISTICS (maximum values) $P_{GM} = 20 \text{ W}$ ($t_p = 20 \mu\text{s}$) $I_{FGM} = 1 \text{ A}$ ($t_p = 20 \mu\text{s}$) $V_{RGM} = 5 \text{ V}$ $P_G(\text{AV}) = 10 \text{ mW}$ $V_{FGM} = 15 \text{ V}$ ($t_p = 20 \mu\text{s}$)**ELECTRICAL CHARACTERISTICS**

Symbol	Types	Test Conditions	Min.	Typ.	Max.	Unit
I_{GT}	TLS106	$T_j = 25^\circ\text{C}$ $V_D = 12 \text{ V}$ $R_L = 140 \Omega$			0.2	mA
	TLS107	Pulse Duration > 20 μs			0.5	
V_{GT}		$T_j = 25^\circ\text{C}$ $V_D = 12 \text{ V}$ $R_L = 140 \Omega$			1.5	V
V_{GD}		$T_j = 110^\circ\text{C}$ $V_D = V_{DRM}$ $R_{GK} = 1 \text{ k}\Omega$	0.1			V
I_H		$T_j = 25^\circ\text{C}$ $I_T = 50 \text{ mA}$ $R_{GK} = 1 \text{ k}\Omega$			5	mA
I_L		$T_j = 25^\circ\text{C}$ $V_D = 12 \text{ V}$ $I_G = 10 \text{ mA}$ $R_{GK} = 1 \text{ k}\Omega$			7	mA
V_{TM}		$T_j = 25^\circ\text{C}$ $I_{TM} = 4 \text{ A}$ $t_p = 10 \text{ ms}$			1.9	V
I_{DRM}		V_{DRM} specified $R_{GK} = 1 \text{ k}\Omega$	$T_j = 25^\circ\text{C}$		0.01	mA
			$T_j = 110^\circ\text{C}$		0.3	
I_{RRM}		V_{RRM} specified $R_{GK} = 1 \text{ k}\Omega$	$T_j = 25^\circ\text{C}$		0.01	mA
			$T_j = 110^\circ\text{C}$		0.3	
t_{gt}		$T_j = 25^\circ\text{C}$ $V_D = V_{DRM}$ $I_T = 4 \text{ A}$ $I_G = 10 \text{ mA}$ $dI_G/dt = 0.1 \text{ A}/\mu\text{s}$			1.5	μs
t_q		$T_j = 110^\circ\text{C}$ $I_T = 4 \text{ A}$ $V_R = 10 \text{ V}$ $V_D = 67\% V_{DRM}$ $di/dt = 10 \text{ A}/\mu\text{s}$ $dv/dt = 10 \text{ V}/\mu\text{s}$ $R_{GK} = 1 \text{ k}\Omega$			100	μs
dv/dt^*		$T_j = 110^\circ\text{C}$ $R_{GK} = 1 \text{ k}\Omega$ Linear Slope up to $V_D = 67\% V_{DRM}$			10	$\text{V}/\mu\text{s}$

* For higher guaranteed values, please consult us.

PACKAGE MECHANICAL DATA

TL Plastic



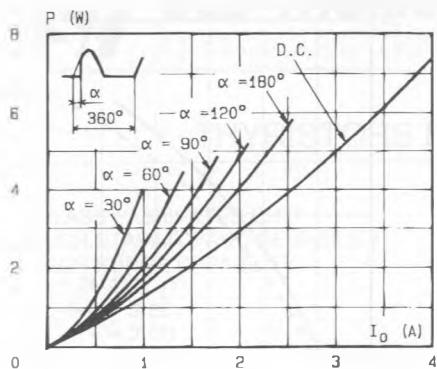


Fig.1 - Maximum mean power dissipation versus mean on-state current.

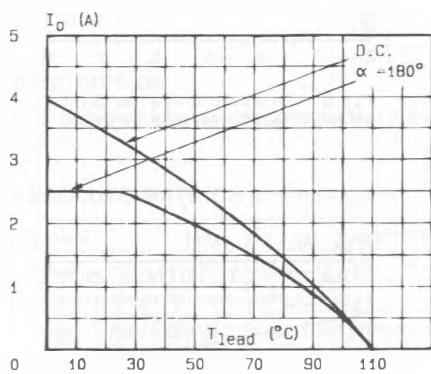


Fig.3 - Mean on-state current versus leads temperature.

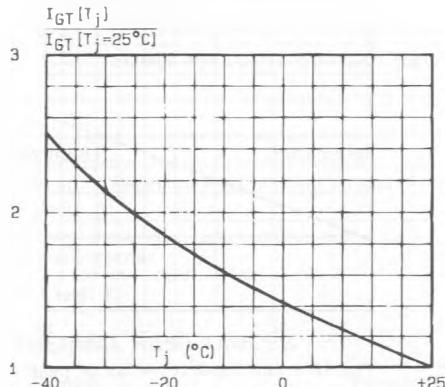


Fig.5 - Relative variation of gate trigger current versus junction temperature.

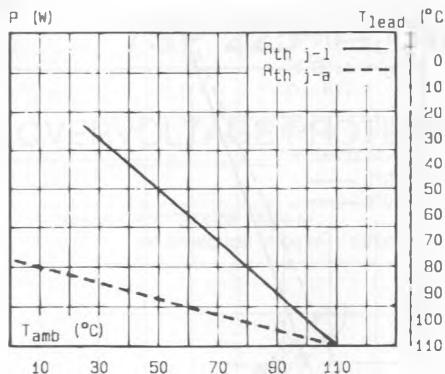


Fig.2 - Correlation between maximum mean power dissipation and maximum allowable temperatures (T_{amb} and T_{lead}).

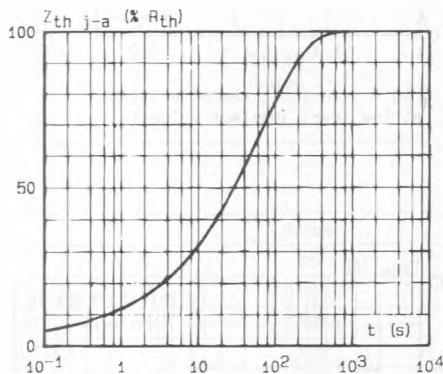


Fig.4 - Thermal transient impedance junction to ambient versus pulse duration.

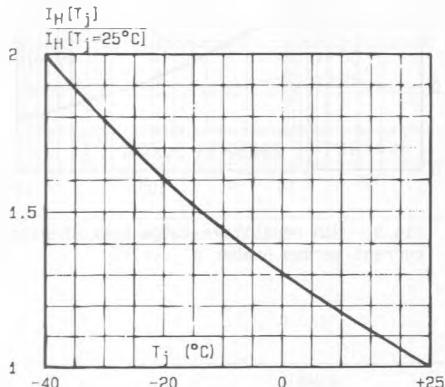


Fig.6 - Relative variation of holding current versus junction temperature.

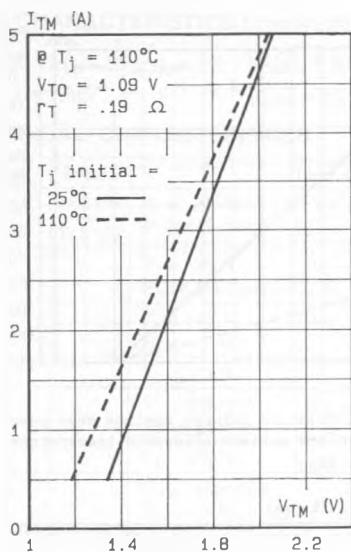


Fig.7 - On-state characteristics at low level (maximum values).

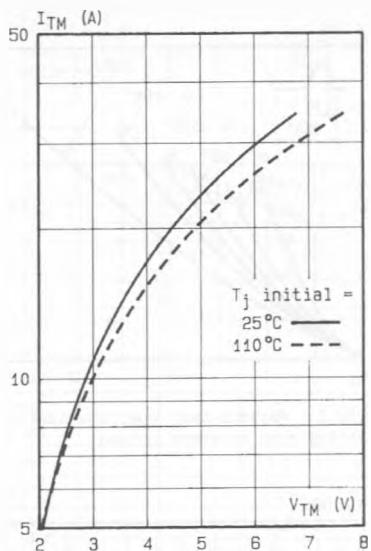


Fig.8 - On-state characteristics at high level (maximum values).

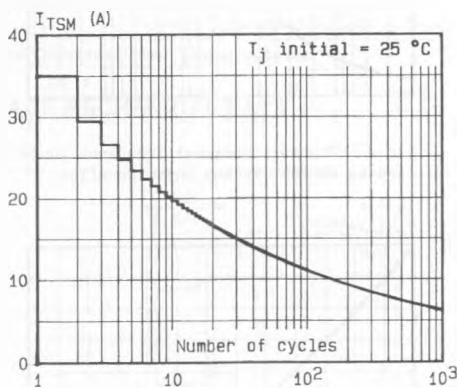
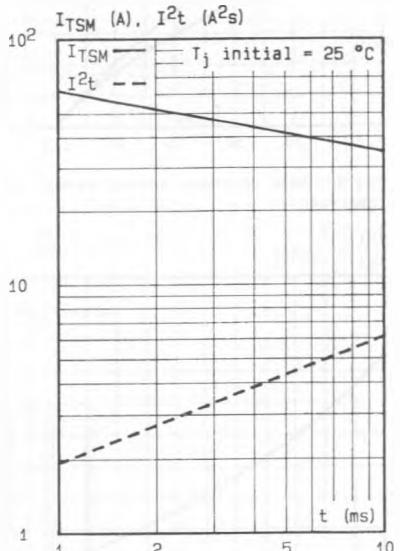


Fig.9 - Non repetitive surge peak on-state current versus number of cycles.

Fig.10 - Non repetitive surge peak on-state current for a sinusoidal pulse with width : $t \leq 10$ ms, and corresponding value of I^2t .